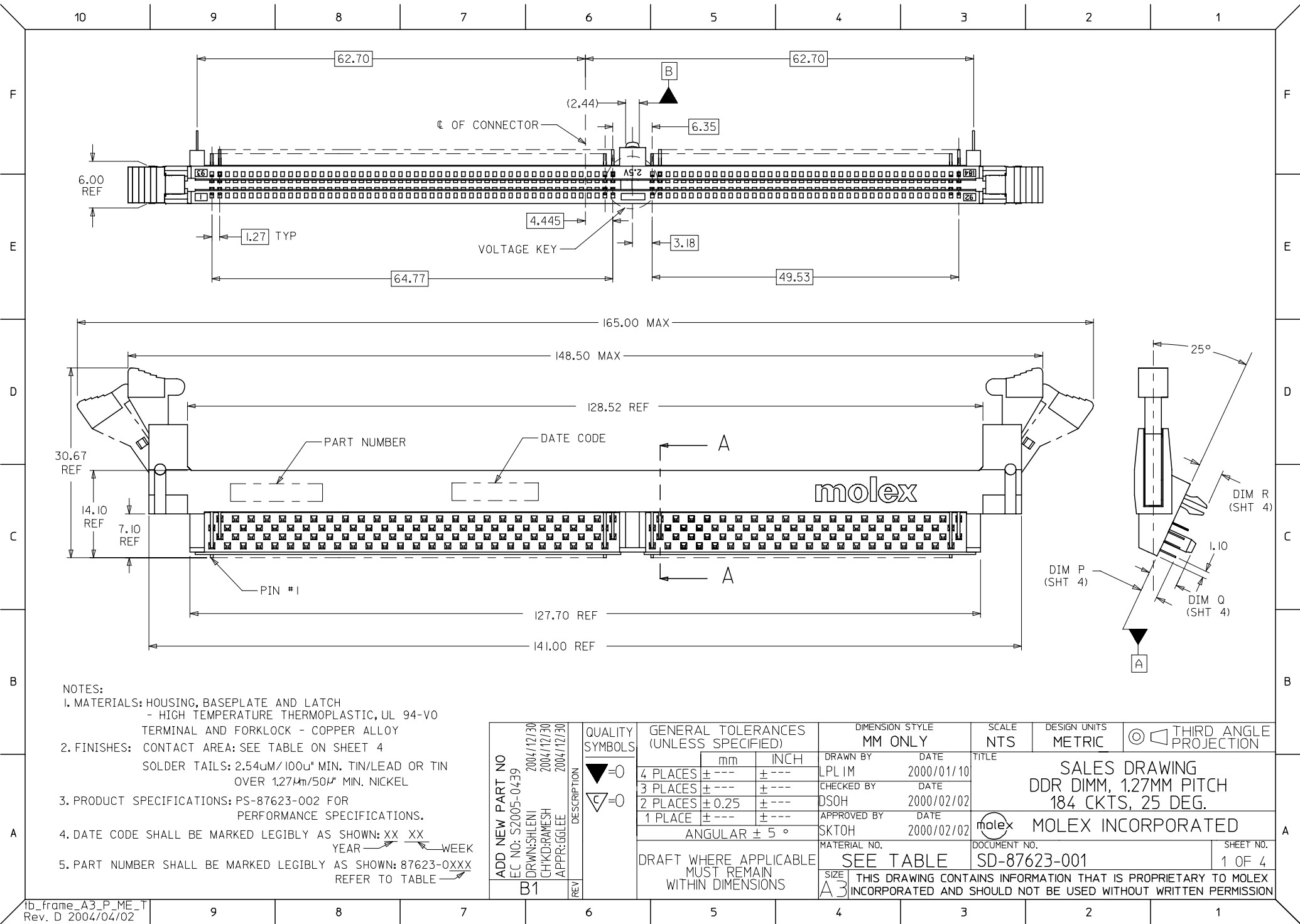
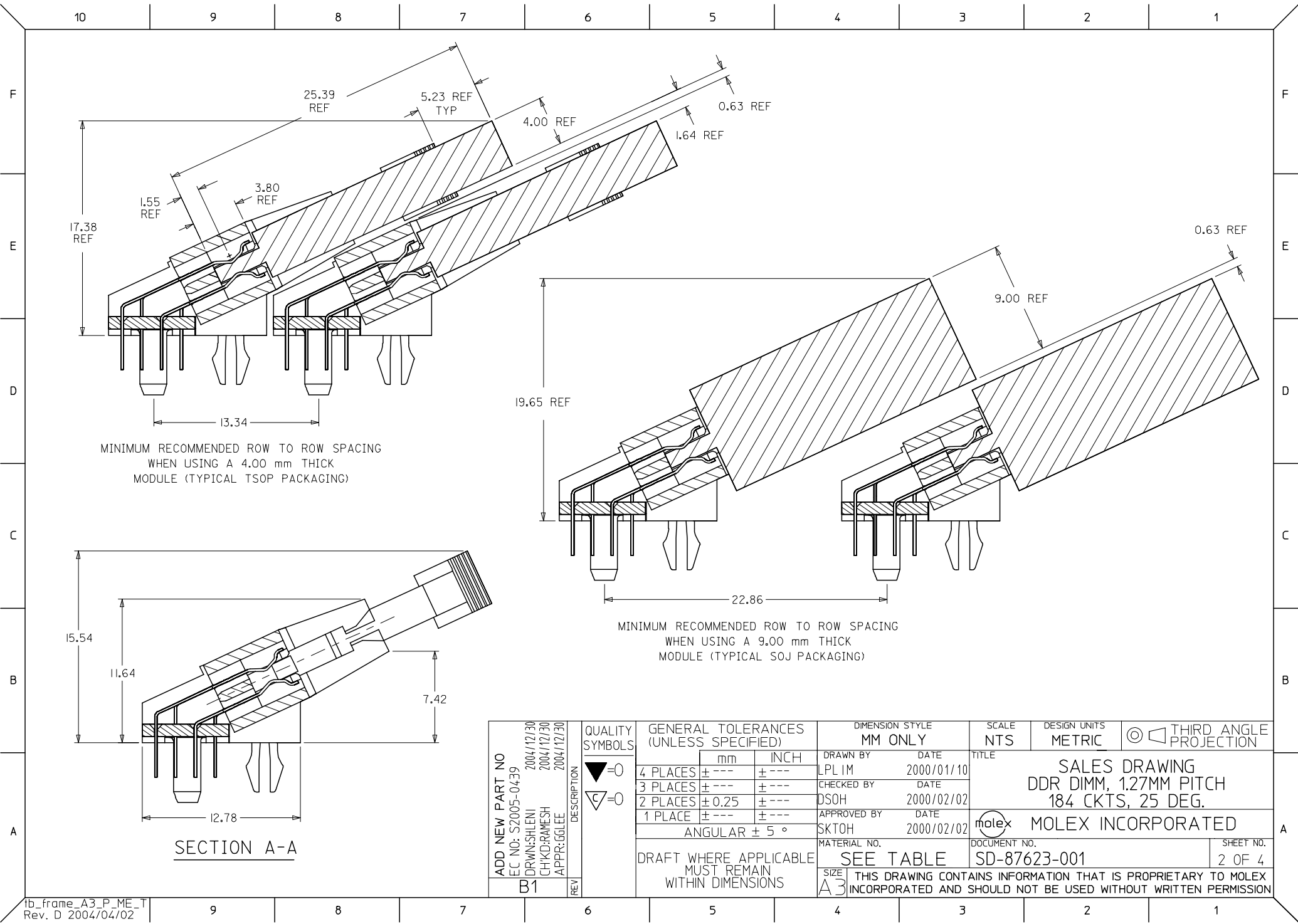




- NOTES:
- MATERIALS: HOUSING, BASEPLATE AND LATCH - HIGH TEMPERATURE THERMOPLASTIC, UL 94-V0
TERMINAL AND FORKLOCK - COPPER ALLOY
 - FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4
SOLDER TAILS: 2.54uM/100u" MIN. TIN/LEAD OR TIN OVER 1.27uM/50u" MIN. NICKEL
 - PRODUCT SPECIFICATIONS: PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
 - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX
YEAR WEEK
 - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX
REFER TO TABLE

ADD NEW PART NO EC NO: S2005-0439 DRWN:SHLENI 2004/12/30 CHKD:RAMESH 2004/12/30 APPR:GGLLEE 2004/12/30 B1	DESCRIPTION	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.  MOLEX INCORPORATED			
			4 PLACES	± ---	± ---	CHECKED BY	DATE				
			3 PLACES	± ---	± ---	DSOH	2000/02/02				
			2 PLACES	± 0.25	± ---	APPROVED BY	DATE				
			1 PLACE	± ---	± ---	SKTOH	2000/02/02				
			ANGULAR ± 5 °			MATERIAL NO.		DOCUMENT NO.			SHEET NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SD-87623-001			1 OF 4			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00 mm THICK
MODULE (TYPICAL TSOP PACKAGING)

MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00 mm THICK
MODULE (TYPICAL SOJ PACKAGING)

SECTION A-A

ADD NEW PART NO EC NO: S2005-0439 DRWN:SHLENI 2004/12/30 CHKD:RAMESH 2004/12/30 APPR:GGLLEE 2004/12/30 REV B1	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.	
			4 PLACES	± ---	± ---	CHECKED BY	DATE		
			3 PLACES	± ---	± ---	DSOH	2000/02/02		
			2 PLACES	± 0.25	± ---	APPROVED BY	DATE	MOLEX MOLEX INCORPORATED	
			1 PLACE	± ---	± ---	SKTOH	2000/02/02		
			ANGULAR ± 5 °		MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87623-001	2 OF 4				
SIZE A3							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

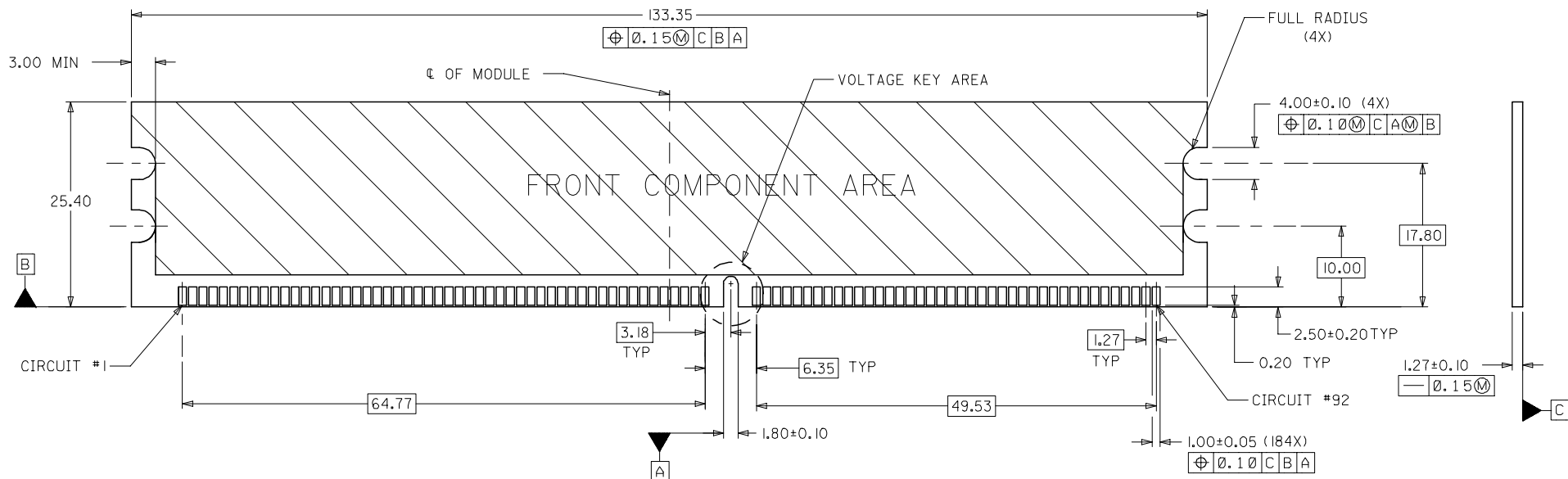
E

D

C

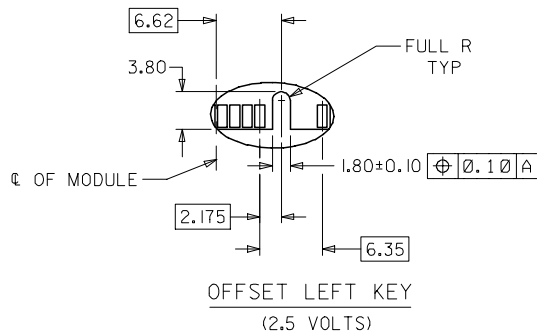
B

A



RECOMMENDED MODULE LAYOUT
(PER JEDEC STANDARD MO-206, 184 CKT.)
UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ± 0.13

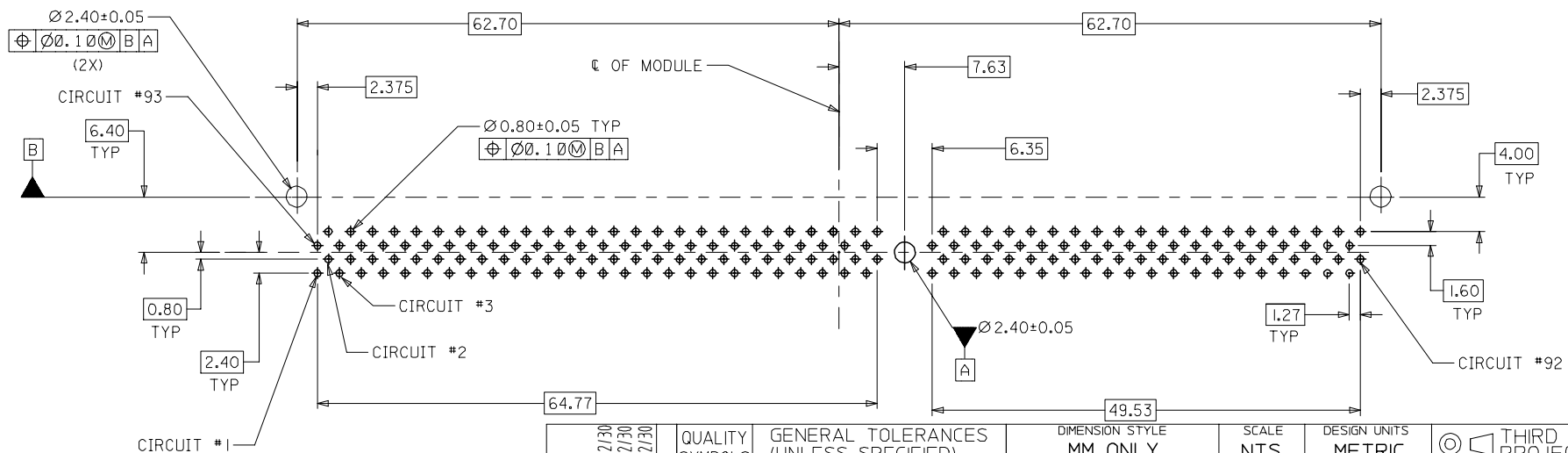
VOLTAGE KEY AREA



ADD NEW PART NO EC NO: S2005-0439 DRWN:SHLENI 2004/12/30 CHKD:RAMESH 2004/12/30 APPR:GGLEE 2004/12/30 REV B1	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.				
					CHECKED BY DSOH	DATE 2000/02/02					
					APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED				
					MATERIAL NO.						
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1

10	9	8	7	6	5	4	3	2
PLATING OPTION	ASSEMBLY PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH Q±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
TIN/LEAD	87623-0001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38uM/15u" MIN. GOLD OVER 1.27uM/50u" MIN. NICKEL
	87623-0011			3.18	4.83	3.94		
	87623-0012			3.18	3.18	3.18		
	87623-0013			3.81	4.83	4.42	2.84	
	87623-0101			2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.76uM/30u" MIN. GOLD OVER 1.27uM/50u" MIN. NICKEL
	87623-0111			3.18	4.83	3.94		
	87623-0113			3.81	4.83	4.42		
	87623-0115			3.18	3.18	3.18	1.57	
TIN	87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38uM/15u" MIN. GOLD OVER 1.27uM/50u" MIN. NICKEL
	87623-2011			3.18	4.83	3.94		
	87623-2012			3.18	3.18	3.18		
	87623-2013			3.81	4.83	4.42	2.84	
	87623-2101			2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.76uM/30u" MIN. GOLD OVER 1.27uM/50u" MIN. NICKEL
	87623-2111			3.18	4.83	3.94		
	87623-2113			3.81	4.83	4.42		
	87623-2115			3.18	3.18	3.18	1.57	



ADD NEW PART NO EC NO: S2005-0439 DRAWN:SHENI CHKD:RAMESH APPR:GGLLEE B1	2004/12/30 2004/12/30 2004/12/30	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
					mm	INCH	DRAWN BY LPL IM		DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.			
				4 PLACES	± ---	± ---	CHECKED BY		DATE 2000/02/02				
				3 PLACES	± ---	± ---	DSOH		DATE 2000/02/02				
				2 PLACES	± 0.25	± ---	APPROVED BY		DATE	MOLEX MOLEX INCORPORATED			
				1 PLACE	± ---	± ---	SKTOH		2000/02/02				
ANGULAR ± 5 °				MATERIAL NO.		DOCUMENT NO.		SHEET NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE		SD-87623-001		4 OF 4					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													